

CLAIMS

1. An epoxy resin molding material for sealing, comprising an epoxy resin, an epoxy resin curing agent, and a pitch.

5

2. The epoxy resin molding material for sealing according to claim 1, wherein the pitch is mesophase microspheres isolated from a mesophase pitch.

10

3. The epoxy resin molding material for sealing according to claim 1 or 2, wherein an electrical resistivity of the pitch is at least $1 \times 10^5 \Omega \cdot \text{cm}$.

15

4. The epoxy resin molding material for sealing according to any one of claims 1 through 3, wherein a carbon content of the pitch is within a range from 88 to 96% by weight.

20

5. The epoxy resin molding material for sealing according to any one of claims 1 through 4, further comprising one or more materials selected from the group consisting of phthalocyanine-based dyes, phthalocyanine-based pigments, aniline black, perylene black, black iron oxide, and black titanium oxide as a colorant that contains no pitch.

25

6. The epoxy resin molding material for sealing according to any one of claims 1 through 5, wherein a combined quantity of the colorant that contains no pitch and the pitch is within a range from 2 to 15% by weight relative to the epoxy resin.

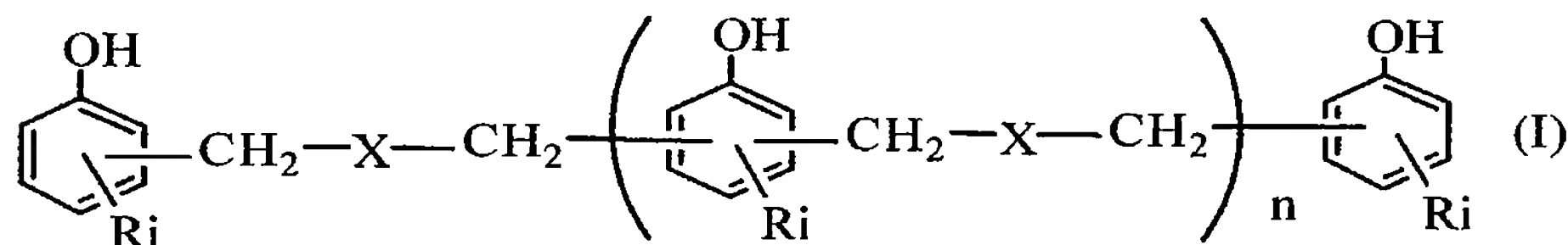
30

7. The epoxy resin molding material for sealing according to any one of claims 1 through 6, wherein a quantity of the pitch relative to the combined quantity of the colorant that contains no pitch and the pitch is at least 30% by weight.

8. The epoxy resin molding material for sealing according to any one of claims 1 through 7, comprising, as the epoxy resin, one or more resins selected from the group consisting of biphenyl type epoxy resins, bisphenol F type epoxy resins, thiodiphenol type epoxy resins, phenol-aralkyl type epoxy resins, and naphthol-aralkyl type epoxy resins.

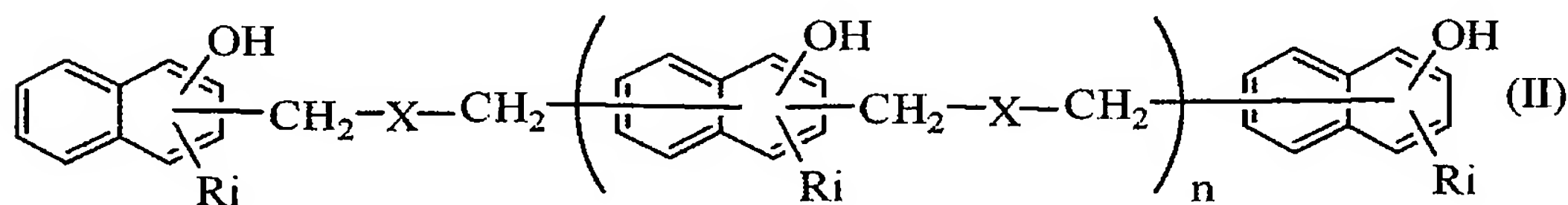
9. The epoxy resin molding material for sealing according to any one of claims 1 through 8, comprising, as the curing agent, one or more resins selected from the group consisting of phenol-aralkyl resins represented by a general formula (I) shown below and naphthol-aralkyl resins represented by a general formula (II) shown below:

[Formula 1]



(wherein, each R represents a hydrogen atom, or a substituted or unsubstituted monovalent hydrocarbon group of 1 to 12 carbon atoms, which may be all identical, or may be different, i represents either 0 or an integer from 1 to 3, X represents a bivalent organic group comprising an aromatic ring, and n represents either 0 or an integer from 1 to 10),

[Formula 2]

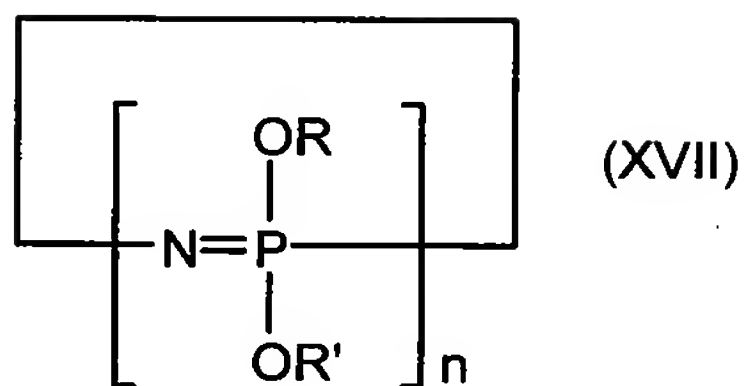


(wherein, each R represents a hydrogen atom, or a substituted or unsubstituted monovalent hydrocarbon group of 1 to 12 carbon atoms, which may be all identical, or may be different, i represents either 0 or an integer from 1 to 3, X represents a bivalent organic group comprising an aromatic ring, and n represents either 0 or an integer from 1 to 10).

10. The epoxy resin molding material for sealing according to any one of claims 1 through 9, further comprising a cyclic phosphazene compound.

11. The epoxy resin molding material for sealing according to claim 10, wherein the cyclic phosphazene compound comprises a compound represented by a general formula (XVII) shown below:

[Formula 3]



(wherein, n represents an integer from 3 to 5, and R and R' each represent an alkyl group of 1 to 4 carbon atoms or an aryl group, which may be either identical or different).

5 12. The epoxy resin molding material for sealing according to claim 11, wherein at least one of R and R' represents a hydroxyphenyl group, and a number of hydroxyphenyl groups is within a range from 1 to 10.

10 13. The epoxy resin molding material for sealing according to any one of claims 10 through 12, comprising a cross-linked cyclic phosphazene compound.

14. An electronic component comprising an element that is sealed with the epoxy resin molding material for sealing according to any one of claims 1 through 13.